Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTIONS:**

1. **1Y**
2. **1A**
3. **1B**
4. **2Y**
5. **2A**
6. **2B**
7. **GND**
8. **3A**
9. **3B**
10. **3Y**
11. **4A**
12. **4B**
13. **4Y**
14. **VCC**

**.052”**

**7**

**8**

**6 5 4 3 2**

**1**

**14**

**13**

**9 10 11 12**

**DIE ID**

**HC 02G**

**.043”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004” X .004”**

**Backside Potential: FLOATING or Vcc**

**Mask Ref: HC 02G**

**APPROVED BY: DK DIE SIZE .043” X .052” DATE: 10/26/20**

**MFG: TEXAS INSTRUMENTS THICKNESS .010” P/N: 54HC02**

**DG 10.1.2**

#### Rev B, 7/19/02